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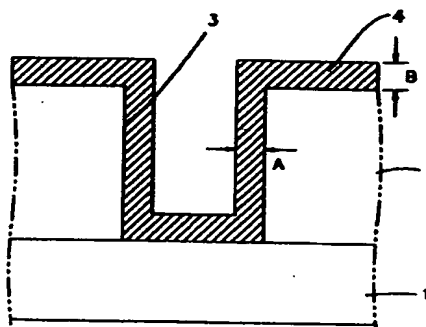
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(54) CVD of silicon containing film using Si₂H₆

(57) A method of forming a thin film for a semiconductor device which applies disilane (Si₂H₆) to chemical vapor deposition is capable of improving deposition rate and step coverage of the thin film although the thin film is deposited at lower temperatures, thereby improving productivity and reliability of the semiconductor device. In order to form various thin films, Si₂H₆ and N₂O, or Si₂H₆ and O₂ are applied for an oxide film, Si₂H₆ and NH₃ for a nitride film, Si₂H₆, N₂O, and NH₃ for a nitride-oxide film, Si₂H₆, O₂, and PH₃ or TMOP for a PSG film, and Si₂H₆, O₂, B₂H₆ or TMOB, and PH₃ or TMOP for a BPSG film. Also, a system for the method according to the present invention is used among an atmospheric pressure chemical vapor deposition system, low pressure chemical vapor deposition system, and plasma chemical vapor deposition system.

FIG. 1



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Description

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0001] The present invention relates to a thin film applied to a semiconductor device, and in particular to an improved method of forming a thin film for a semiconductor device, which applies disilane (Si_2H_6) to chemical vapor deposition, capable of improving deposition rate and step coverage of the thin film although the thin film is deposited at low temperature.

2. Description of the Conventional Art

[0002] Generally, a fabrication process for a semiconductor device mainly includes forming a thin film, and patterning the thin film. The thin film which is provided in order to fabricate the semiconductor device may be divided into insulating film, dielectric film, conductive film, planarized film, and passivation film, etc. according to requirements. Most common materials for the dielectric film are Silicon oxide (SiO_2) and silicon nitride (Si_3N_4), for the conduction film are polysilicon and tungsten silicide (WxSiy), for the insulation film are silicon oxide (SiO_2) and phospho silicate glass (PSG), for the planarized film are phospho silicate glass (PSG) and borophospho silicate glass (BPSG), and silicon nitride is applied for the protection film.

[0003] Among methods for depositing the thin film, that is, physical deposition, vacuum deposition, chemical vapor deposition (CVD), and sputtering, etc., the CVD is the most common method. According to the CVD for forming the thin film, material gas is induced onto a substrate, and particles reacted on the substrate or in vapor are diffused on the surface of the substrate. The most common CVD equipments are atmospheric pressure chemical vapor deposition (APCVD) equipment, low pressure chemical vapor deposition (LPCVD) equipment, and plasma-enhanced chemical vapor deposition (PECVD or plasma deposition) equipment.

[0004] First, the APCVD applying the atmospheric pressure chemical vapor deposition (APCVD) equipment, which has been firstly developed for forming a polysilicon layer for a bipolar device, deposits a polysilicon thin film by pyrolyzing polysilicon (SiH_4) at atmospheric pressure, 760 torr, at low temperature. The APCVD equipment performs the APCVD at low temperature and has a fast deposition rate, but has nonconformal step coverage and a high contamination possibility of particles by gaseous reaction. The APCVD, the most common CVD technique, is mainly applied to silicon oxide (SiO_2), phospho silicate glass (PSG), borophospho silicate glass (BPSG), or polysilicon epitaxy deposition.

[0005] The low pressure chemical vapor deposition (LPCVD) applying the LPCVD equipment has improved step coverage compared to the APCVD and a thickness uniformity of the thin film, but has a slow deposition rate, thus dropping mass productivity, and requires high temperature. The LPCVD is applied to polysilicon, silicon oxide (SiO_2), oxide nitride (SiOxNy), phospho silicate glass (PSG), or borophospho silicate glass (BPSG) deposition. To improve the defects of the LPCVD equipment which is processed at high temperature, there has been provided the plasma-enhanced chemical vapor deposition (PECVD) equipment. The PECVD equipment applies an energy for reaction acceleration to material gas as well as heat in order to avoid the high temperature process. The PECVD using the PECVD equipment is performed at low temperature by discharging electricity in a reaction chamber at reduced pressure (about 10-100Pa) for the reaction acceleration, thereby discharging plasma and exciting gaseous molecules into activation state. The most common plasma CVD is to generate the plasma by applying high frequency to a parallel-plate type electrode. Here, a frequency range for generating the plasma is between 50KHz and 15.56MHz. Since the PECVD is relatively performed at low temperatures and has a rapid deposition rate, it is most widely used thereamong.

[0006] When forming thin films such as oxide film, polysilicon film, tungsten silicide film, phospho silicate glass (PSG) film, and borophospho silicate glass (BPSG) film, etc., polysilicon (SiH_4) or tetra-ethyl-ortho-silicate (TEOS) is generally used as material gas. Table 1 shows the deposition conditions- material gas, temperature, and pressure- by each CVD equipment. Table 2 shows the step coverage and deposition rate of each thin film which is deposited in accordance with Table 1. That is, in order to form a conventional oxide film, material gases among TEOS and O_2 , TEOS and O_3 , SiH_4 and N_2O , or SiH_4 and O_2 , are applied regardless of any kind of the CVD equipments. The temperature and pressure applied to each CVD equipment are as shown in Table 1. Namely, in case of the LPCVD equipment, the thin film is deposited under about 1.0 torr at about 430 to 800°C, and in the PECVD equipment, the thin film is deposited under 3.0 torr at temperature lower than 450°C. Also, the APCVD equipment performs the deposition at atmospheric pressure at temperature lower than 450°C.

[0007] In addition, dischlorosilane (SiH_2Cl_2) and NH_3 , or SiH_4 and NH_3 are used for depositing the nitride film. Here, the LPCVD equipment has the conditions of about 700°C and 0.4 torr, and the PECVD equipment has the conditions of temperatures lower than 450°C and pressures lower than 3.0 torr.

[0008] In order to form the PSG or BPSG film which is the planarized film, TEOS, O₂ or O₃, and PH₃ or tetra-methyl-ortho-phosphorus (TMOP); and TEOS, O₂ or O₃, B₂H₆ or tetra-methyl-ortho-boron (TMOB), and PH₃ or TMOP are applied to material gases, respectively. In case of the LPCVD equipment, the deposition is performed at 1.0 to 4.0 torr at 610 to 700°C, and the PECVD equipment has the conditions of temperatures lower than about 450°C and pressures below 3.0 torr, the APCVD equipment has the condition of temperatures lower than 450°C. Here, in the Tables 1 and 2, the gas in the bracket, (), may replace the gas outside the bracket. That is, in case of O₂(O₃), O₃ may replace O₂.

[Table.1]

	gas	deposition method					
		LPCVD		PECVD		APCVD	
		temper- ature (°C)	pressu-re (torr)	temper-ature (°C)	pressu-re (torr)	temper-ature (°C)	pressu-re (torr)
oxide film	TEOS/O ₂	~700	~0.3	≤450	≤3.5	≤450	atmos- pheric pres- sur-e
	SiH ₄ /N ₂ O	~800	~1.0	≤450	≤3.0	x	x
	SiH ₄ /O ₂	~430	~0.3	x	x	≤450	atmos- pheric pres- sur-e
nitride film	DCS/NH ₃	~700	~0.4	x	x	x	x
	SiH ₄ /NH ₃	~700	~0.4	≤450	≤3.0	x	x
BPSG	TEOS/O ₂ (O ₃)/PH ₃ (TM O P)/TMOB	~610	~1.0	≤450	2.3-2.8	≤450	atmos- pheric pres- sur-e
W _x Si _y	SiH ₄ /WF ₆	200~650	0.2~2	x	x	x	x

[Table.2]

	gas	deposition method					
		LPCVD		PECVD		APCVD	
		deposition rate (Å/min)	step cov- erag-e (%)	deposition rate (Å/min)	step cov- erag-e (%)	deposition rate (Å/min)	step cov- erag-e (%)
oxide film	TEOS/O ₂	~100	~90	3000~8000	≤60	≤4000	≤60
	SiH ₄ /N ₂ O	≤30	~100	3000~8000	≤60	x	x
	SiH ₄ /O ₂	~100	≤60	x	x	~3000	≤60
nitride film	DCS/NH ₃	~30	~100	x	x	x	x
	SiH ₄ /NH ₃	x	x	~3000~8000	≤60	x	x
BPSG	TEOS/O ₂ (O ₃)/PH ₃ (TM O P)/TMOB	~200	~80	3000~5000	~75	3000~5000	~80

[0009] However, when applying the conventional method of forming the thin film, that is, when using the method of forming the thin film according to the condition as shown in [Table.1], the thin film has slow deposition rate and low step coverage, as shown in [Table.2].

SUMMARY OF THE INVENTION

[0010] Accordingly, it is an object of the present invention to provide a method of forming a thin film for a semiconductor device capable of improving deposition rate and step coverage of a thin film by applying disilane (Si_2H_6) as material gas instead of SiH_4 or TEOS.

[0011] Additional advantages, objects and features of the invention will become more apparent from the description which follows.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] The present invention will become more fully understood from the detailed description given hereinbelow and the accompanying drawings which are given by way of illustration only, and thus are not limitative of the present invention, and wherein:

Figure 1 is a vertical cross-sectional view of a semiconductor substrate for illustrating step coverage.

DETAILED DESCRIPTION OF THE INVENTION

[0013] Table. 3 shows the conditions of a method of forming a thin film for a semiconductor device according to the present invention by each process equipment, and Table. 4 shows the deposition rate and step coverage of each thin film obtained under the condition as shown in Table.3. Here, the step coverage was observed as shown in Figure 1. That is, an insulating film 2 is formed on a semiconductor substrate 1, and a cavity 3 is made by etching a predetermined area of the insulating film 2. At this time, when a thickness of a portion of a thin film 4 which is fixed to a side wall of the cavity 3 is A and a thickness of a portion of the film 4 which is formed on an upper surface of the insulating film 2 is B, an equation of the step coverage is $A / B \times 100 = \text{step coverage (\%)}$. That is, when A and B has a same thickness, the step coverage is 100%, and higher step coverage is more suitable for a high-integrated semiconductor device.

[Table. 3]

	gas	deposition method					
		LPCVD		PECVD		APCVD	
		temperature (°C)	pressure (torr)	temperature (°C)	pressure (torr)	temperature (°C)	pressure (torr)
oxide film	$\text{Si}_2\text{H}_6/\text{N}_2\text{O}$	500-800	0.1-9	150-750	0.1-9	x	x
	$\text{Si}_2\text{H}_6/\text{O}_2$	300-700	0.1-9	x	x	200-650	atmospheric pressure
nitride film	$\text{Si}_2\text{H}_6/\text{NH}_3$	350-800	0.1-9	150-750	0.1-9	x	x
nitride-oxide film	$\text{Si}_2\text{H}_6/\text{NH}_3/\text{N}_2\text{O}$	350-800	0.1-9	150-750	0.1-9	x	x
BPSG	$\text{Si}_2\text{H}_6/\text{PH}_3/\text{O}_2/\text{TMOB}$	250-800	0.1-9	150-750	0.1-9	200-650	atmospheric pressure
	$\text{Si}_2\text{H}_6/\text{TMO}/\text{P}/\text{TMOB}$	250-800	0.1-9	150-750	0.1-9	200-650	atmospheric pressure
PSG	$\text{Si}_2\text{H}_6/\text{O}_2/\text{P}/\text{H}_3$ (TMOP)	200-700	0.1-9	150-750	0.1-9	200-650	atmospheric pressure
W_xSi_y	$\text{Si}_2\text{H}_6/\text{WF}_6$	200-650	0.1-9	x	x	x	x

9 torr. Disilane was flowed into the chamber at 50 to 800scm, and tetra-methyl-ortho-phosphorus (TMOP) or phosphine (PH_3) at 150 to 2400scm, tetra-methyl-ortho-boron (TMOB) or diborane (B_2H_6) at 15 to 200scm, and O_2 at 15 to 400scm, thus forming the BPSG film. The deposition rate of the BPSG film obtained by the above condition according to the present invention was 50 to 9000 Å/min, showing much improvement compared to that of the conventional BPSG film obtained by the condition applying TEOS, O_2 or O_3 , PH_3 or TMOP, and B_2H_6 or TMOB, which was 200 Å/min. Also, the step coverage of the BPSG film according to the present invention was 90% while the step coverage of the conventional BPSG film was 80%. Although the BPSG film was deposited at low temperature, the properties and growth rate of the thin film were improved.

[0026] A PSG film was deposited under condition that temperatures and pressures in the reaction chamber ranged between 200 and 700°C and between 0.1 and 9 torr, respectively. Disilane, and TMOP(PH_3) and O_2 were flowed into the reaction chamber at 50 to 800 scm and at 15 to 500 scm, respectively. Here, more desirable pressure range for depositing the PSG film according to the present invention is from 0.3 to 5 torr. Under the above condition, the deposition rate of the PSG film was 50 to 6000 Å/min, and the step coverage thereof was over 90%.

[0027] A tungsten silicide (WxSi_y) film, which is widely applied to a gate electrode of a MOS memory device, was deposited at 0.1 to 9 torr and at temperatures ranged from 200 to 650°C by using disilane and WF_6 . The thusly formed tungsten silicide film had lower resistance compared to the conventional tungsten silicide film using SiH_4 and WF_6 , and higher step coverage than the conventional tungsten silicide film. Also, the tungsten silicide film according to the present invention had a big grain size.

[0028] Second, condition of a method of forming the thin film by using a PECVD equipment will be described.

[0029] An oxide (SiO_2) film was formed under such condition as follows. Temperatures in the reaction chamber ranged between 150 and 750°C, pressures were 0.1 to 9 torr, and disilane and N_2O were flowed into the chamber at 50 to 500scm and 100 to 5000scm, respectively. Here, more desirable pressures are 0.2 to 5.3 torr. The deposition rate of the oxide film was 50 to 9000 Å/min which was improved more than that of the conventional oxide film, 3000 to 8000 Å/min, and the step coverage was 90%, much improved than the conventional step coverage which was less than 60%.

[0030] Next, a nitride (Si_3N_4) film was deposited at 0.1 to 9 torr at temperatures ranged between 150 and 750°C. Also, disilane was flowed into the reaction chamber at 10 to 500scm and ammonia (NH_3) at 15 to 2000scm. At this time, more desirable pressures are 0.1 to 5.5 torr. According to the present invention, the deposition rate of the oxidation film was 50 to 9000 Å/min, and the step coverage was over 95%, which were both improved compared to the conventional method of forming the nitride film applying SiH_4 and NH_3 .

[0031] A nitride-oxide (SiOxNy) film was deposited at pressures from 0.1 to 9 torr. Temperatures in the reaction chamber ranged between 150 and 750°C, and disilane and ammonia (NH_3) are flowed into the reaction chamber.

[0032] Next, a BPSG film was deposited under condition as follows.

[0033] Temperatures in the reaction chamber ranged from 250 to 800°C, and pressures therein were between 0.1 and 9 torr. Disilane was flowed into the chamber at 70 to 1000scm, and tetra-methyl-ortho-phosphorus (TMOP) or phosphine (PH_3) at 150 to 3000scm, tetra-methyl-ortho-boron (TMOB) or diborane (B_2H_6) at 15 to 300scm, and O_2 at 15 to 500scm, thus forming the BPSG film. The deposition rate of the BPSG film obtained by the above condition according to the present invention was 50 to 9000 Å/min, showing much improvement compared to that of the conventional BPSG film obtained by the condition applying TEOS, O_2 or O_3 , PH_3 or TMOP, and B_2H_6 or TMOB, which was 3000 to 5000 Å/min. Also, the step coverage of the BPSG film according to the present invention was over 90% while the step coverage of the conventional BPSG film was about 75%.

[0034] A PSG film was deposited at pressures from 0.1 to 9 torr. Temperatures in the reaction chamber ranged between 150 and 700°C, and TMOP or PH_3 , and O_2 were flowed into the reaction chamber at 50 to 1000scm and at 15 to 500scm, respectively. Here, the deposition rate of the PSG film according to the present invention was 50 to 9000 Å/min and the step coverage was over 90%.

[0035] Lastly, condition of a method of forming the thin film by using an APCVD equipment will be described.

[0036] An oxide (SiO_2) film was deposited at atmospheric pressure at 200 to 650°C, and disilane and O_2 were flowed into the reaction chamber. Here, the deposition rate of the oxide film according to the present invention ranged between 500 and 5000 Å/min, and the step coverage thereof was over 80%, showing much improvement compared to that of the conventional oxide film which was 60%.

[0037] A BPSG film was deposited at atmospheric pressure at 200 to 650°C, and disilane, TMOP or PH_3 , TMOB or B_2H_6 , and O_2 were respectively flowed into the reaction chamber. Here, the deposition rate of the BPSG film according to the present invention ranged between 500 and 5000 Å/min, and the step coverage thereof was over 90%, which were both improved than the conventional BPSG film.

[0038] A PSG film was deposited at atmospheric pressure at 200 to 650°C, and disilane, TMOP or PH_3 , and O_2 were flowed into the reaction chamber. Here, the step coverage of the PSG film according to the present invention was over 90%, showing much improvement compared to the conventional PSG film.

[0039] In accordance with data from Tables 3 and 4, the deposition rate and step coverage of the thin film according to present invention were improved by applying disilane to various the chemical vapor depositions for forming the thin

film, because combination structure of disilane is less stable than silane (SiH_4) and is easily diffused at low temperatures, thus having a rapid gas diffusion rate, and accordingly a rapid deposition rate of the thin film.

[0040] As described above, the method of forming the thin film for the semiconductor device according to the present invention is capable of improving the deposition rate and step coverage of the thin film by applying disilane to the chemical vapor deposition, thereby improving productivity and reliability of the semiconductor device.

[0041] Although the preferred embodiment of the present invention has been disclosed for illustrative purposes, those skilled in the art will appreciate that various modifications, additions and substitutions are possible, without departing from the scope and spirit of the invention as recited in the accompanying claims.

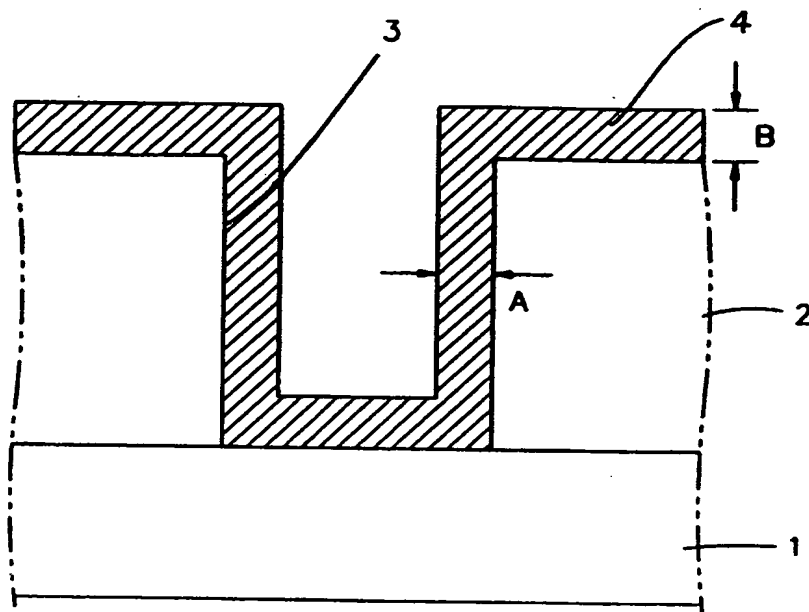
10 Claims

1. In a process wherein a semiconductor substrate is put into a reaction chamber of a chemical vapor deposition equipment and the reaction chamber is maintained at predetermined pressures and temperatures, and thus a thin film is formed on the semiconductor substrate, a method of forming a thin film for a semiconductor device applying disilane as main material gas.
2. The method of claim 1, wherein the thin film is one of oxide, nitride, nitride-oxide, borophospho silicate glass (BPSG), phospho silicate glass (PSG), and tungsten silicide films.
3. The method of claim 2, wherein a method of forming the oxide film applies a chemical vapor deposition (CVD) equipment applying disilane and nitrogen oxide (N_2O).
4. The method of claim 3, wherein the CVD equipment is a low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 500 and 800°C and pressures are 0.1 to 9 torr.
5. The method of claim 3, wherein the CVD equipment is a plasma chemical vapor deposition (PCVD) equipment, and temperatures in the reaction chamber range between 150 and 750°C and pressures are 0.1 to 9 torr.
6. The method of claim 2, wherein a method of forming the oxide film applies the chemical vapor deposition (CVD) equipment applying disilane and oxygen (O_2).
7. The method of claim 6, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 300 and 700°C and pressures are 0.1 to 9 torr.
8. The method of claim 6, wherein the CVD equipment is an atmospheric pressure chemical vapor deposition (APCVD) equipment, and temperatures in the reaction chamber range between 200 and 650°C and pressure is atmospheric pressure.
9. The method of claim 2, wherein a method of forming the nitride film applies the chemical vapor deposition (CVD) equipment using disilane and ammonia (NH_3).
10. The method of claim 9, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 350 and 800°C and pressures are 0.1 to 9 torr.
11. The method of claim 9, wherein the CVD equipment is the plasma chemical vapor deposition (PCVD) equipment, and temperatures in the reaction chamber range between 150 and 750°C and pressures are 0.1 to 9 torr.
12. The method of claim 2, wherein a method of forming the nitride-oxide film applies the chemical vapor deposition (CVD) equipment applying disilane, ammonia (NH_3), and nitrogen oxide (N_2O).
13. The method of claim 12, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 350 and 800°C and pressures are 0.1 to 9 torr.
14. The method of claim 12, wherein the CVD equipment is the plasma chemical vapor deposition (PCVD) equipment, and temperatures in the reaction chamber range between 150 and 750°C and pressures are 0.1 to 9 torr.
15. The method of claim 2, wherein a method of forming the BPSG film applies the chemical vapor deposition (CVD)

equipment applying disilane, phosphine (PH_3), oxygen (O_2), and TMOB, or applying disilane, TMOP, O_2 , and TMOB.

- 5 16. The method of claim 15, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 250 and 800°C and pressures are 0.1 to 9 torr.
- 10 17. The method of claim 15, wherein the CVD equipment is the plasma chemical vapor deposition (PCVD) equipment, and temperatures in the reaction chamber range between 150 and 750°C and pressures are 0.1 to 9 torr.
- 15 18. The method of claim 15, wherein the CVD equipment is the atmospheric pressure chemical vapor deposition (APCVD) equipment, and temperatures in the reaction chamber range between 200 and 650°C and pressure is atmospheric pressure.
- 20 19. The method of claim 2, wherein a method of forming the PSG film applies the chemical vapor deposition (CVD) equipment using disilane, oxygen (O_2), and phosphine (PH_3), or applying disilane, oxygen (O_2), and TMOP.
- 25 20. The method of claim 19, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 200 and 700°C and pressures are 0.1 to 9 torr.
- 30 21. The method of claim 19, wherein the CVD equipment is the plasma chemical vapor deposition (PCVD) equipment, and temperatures in the reaction chamber range between 150 and 750°C and pressures are 0.1 to 9 torr.
- 35 22. The method of claim 19, wherein the CVD equipment is the atmospheric pressure chemical vapor deposition (APCVD) equipment, and temperatures in the reaction chamber range between 200 and 650°C and pressure is atmospheric pressure.
- 40 23. The method of claim 2, wherein a method of forming the tungsten silicide film applies the chemical vapor deposition (CVD) equipment using disilane and tungstenfluoride (WF_6).
- 45 24. The method of claim 23, wherein the CVD equipment is the low pressure chemical vapor deposition (LPCVD) equipment, and temperatures in the reaction chamber range between 200 and 650°C and pressures are 0.1 to 9 torr.
- 50
- 55

FIG. 1





European Patent
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EUROPEAN SEARCH REPORT

Application Number
EP 98 10 1539

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.6)
X	US 5 098 865 A (MACHADO JOSE R ET AL) 24 March 1992 * column 7, line 66 - column 8, line 65 *	1-5	H01L21/316 H01L21/314 H01L21/318 H01L21/285 H01L21/205
X	JUHO SONG ET AL: "STRUCTURAL PROPERTIES OF LOW TEMPERATURE PLASMA ENHANCED CHEMICAL VAPOR DEPOSITED SILICON OXIDE FILMS USING DISILANE AND NITROUS OXIDE" APPLIED PHYSICS LETTERS, vol. 67, no. 20, 13 November 1995, pages 2986-2988, XP000544313 * the whole document *	1-3,5	
X	EP 0 256 337 A (IBM) 24 February 1988 * abstract *	1,2,23,24	
X	SAITO T ET AL: "KINETIC STUDY OF WSI-CVD PROCESSES - A COMPARISON OF WF6/SiH4 AND WF6/Si2H6 REACTION SYSTEMS" ELECTRONICS & COMMUNICATIONS IN JAPAN, PART II - ELECTRONICS, vol. 78, no. 10, 1 October 1995, pages 73-84, XP000553256 * the whole document *	1,2,23,24	TECHNICAL FIELDS SEARCHED (Int.Cl.6) H01L C23C
X	JASINSKI J M ET AL: "EXCIMER LASER-INDUCED DEPOSITION OF SILICON NITRIDE THIN FILMS" JOURNAL OF APPLIED PHYSICS, vol. 61, no. 1, 1 January 1987, pages 431-433, XP000068645 * the whole document *	1,2,9-11	
-/-			
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 29 June 1998	Examiner Königstein, C
<p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons Δ : member of the same patent family, corresponding document</p>			

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, 257/E21.293

ABSTRACT:

CHG DATE=19990902 STATUS=O> A method of forming a thin film for a semiconductor device which applies disilane (Si₂H₆) to chemical vapor deposition is capable of improving deposition rate and step coverage of the thin film although the thin film is deposited at lower temperatures, thereby improving productivity and reliability of the semiconductor device. In order to form various thin films, Si₂H₆ and N₂O, or Si₂H₆ and O₂ are applied for an oxide film, Si₂H₆ and NH₃ for a nitride film, Si₂H₆, N₂O, and NH₃ for a nitride-oxide film, Si₂H₆, O₂, and PH₃ or TMOP for a PSG film, and Si₂H₆, O₂, B₂H₆ or TMOB, and PH₃ or TMOP for a BPSG film. Also, a system for the method according to the present invention is used among an atmospheric pressure chemical vapor deposition system, low pressure chemical vapor deposition <